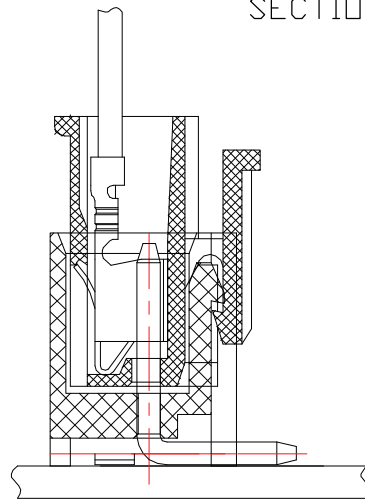
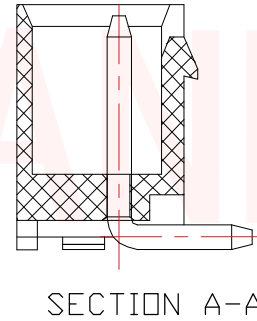
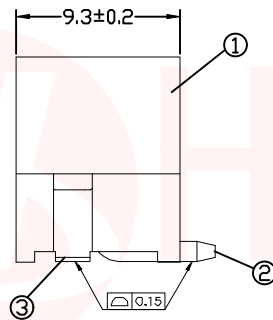
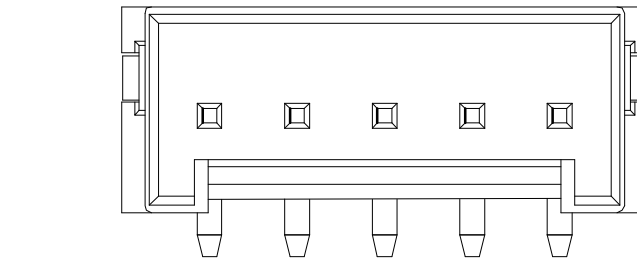
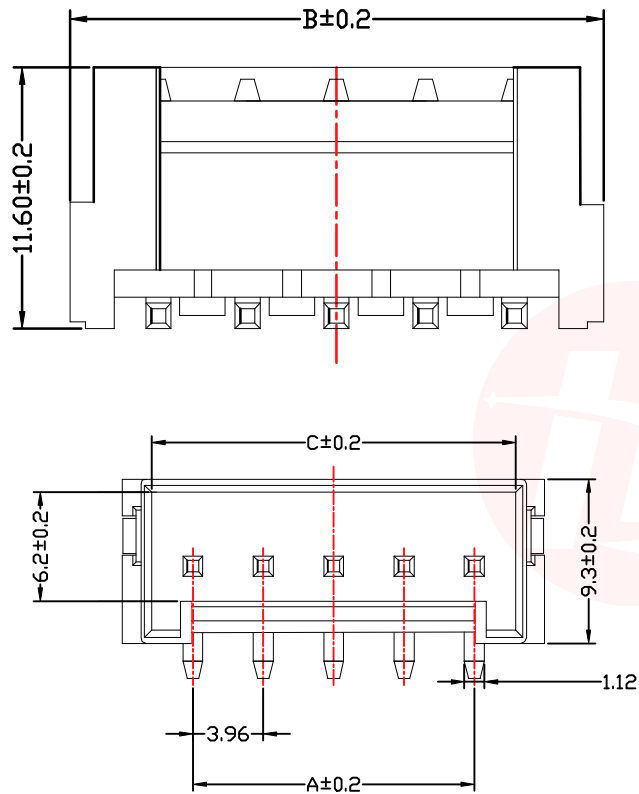




REV.	ECN NO OR DESCRIPTION	REVISED	DATE



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

技术要求:

- 1、塑件材料: LCP (UL-94V-0)
- 2、接触件: 黄铜镀锡
- 3、接触电阻: $\leq 30m\Omega$
- 4、绝缘电阻: $\geq 1000M\Omega$
- 5、额定电压: 250V AC DC
- 6、额定电流: 7.0A AC DC
- 7、耐压: 能承受1000V AC/Min ute
- 8、工作温度: $-25^{\circ}\sim+85^{\circ}$
- 9、可焊性试验: 浸锡面积 $\geq 95\%$ 温度260,时间 2.5 ± 0.5 秒
- 10、铅和镉等六大有害物质含量要符合环保要求

TABLE:

CSG PART NO.	Dimension mm			
	PIN	A	B	C
WAFER-VH396L-2A	2P	3.96	11.88	8.60
WAFER-VH396L-3A	3P	7.92	15.84	12.56
WAFER-VH396L-4A	4P	11.88	19.80	16.52
WAFER-VH396L-5A	5P	15.84	23.76	20.48
WAFER-VH396L-6A	6P	19.80	27.72	24.44
WAFER-VH396L-7A	7P	23.76	31.68	28.40
WAFER-VH396L-8A	8P	27.72	35.64	32.36
WAFER-VH396L-9A	9P	31.68	39.60	36.32
WAFER-VH396L-10A	10P	35.64	43.56	40.28

3	焊片/Fitting Nail	黄铜	电镀(锡): 整个表面镀底镍 30U"MIN 再镀锡80U" MIN
2	端子/Contact	黄铜	电镀(锡): 整个表面镀底镍 30U"MIN 再镀锡80U" MIN
1	基座/Wafer	LCP (UL94V-0)	30U"MIN 再镀锡80U" MIN
序号	名称	材料	米色

UNLESS OTHERWISE
SPECIFIED TOLERANCES



东莞市汉博电子科技有限公司
DONGGUAN HANBO TECHNOLOGY CO., LTD

DECIMALS: ANGLES:
X :±0.20 X :±2°
X.X :±0.10 X.X :±1°
X.XX :±0.05

TITLE	WAFER VH 3.96MM 立贴 SMT TYPE		
DWN	xiong	PART NO. WAFER-VH396L-NA	
CHKD	lee	SCALE:1:1	UNIT: mm
APVD	wang	SIZE: A4	SHEET:10F 1
REV: A4			

CUSTOMER COPY